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## **CLAIM AMENDMENTS**

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(Currently amended) A tamper evident RFID tag, comprising:

a tamper evident label material, with

an adhesive on a back side, and

an RFID Transponder adhered to said adhesive, wherein:

the tamper exident label material is a vinyl with a tensile and tear resistance such that the tamper evident label material one of tears and breaks upon an attempted removal from a substrate.

(Cancelled)

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(Original) The tag of claim 1, wherein:

the tamper evident label material is 3M 7610 ScotchMark Destructible Vinyl.

- 4. (Original) The tag of claim 1, further including: a release liner attacked to said adhesive.
- 5. (Original) The tag of claim 1, further including: a hologram on the label material.
- (Original) The tag of claim 1, further including:
   microprinting on the label material.
- 7. (Currently amended) A tamper evident RFID tag, comprising a <u>clear</u> label material, with a silicone pattern and <u>an a pigmented</u> adhesive on a back side, and an RF transponder adhered to said adhesive;

wherein separation of the tag from a substrate results in incomplete separation of the adhesive in the form of the silicone pattern <u>and said pattern becomes visible</u>.

8. (Original) The tag of claim 7, wherein: the tamper evident label material is one of 3M 7866, 3M 7389 and 3M 7385.

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- (Original) The tag of claim 8, further including:
   a hologram on the latel material.
- 10. (Currently amended) The tag of claim 9 8, further including: microprinting on the label material.
- 11. (Currently amended) A tamper evident RF transponder, comprising
  a base film with a printed antenna and an integrated circuit chip on a front surface;
  the base film having propogation tear cuts at one or more edges of the base film
  whereby attempted removal of the RF transponder from a substrate causes the propogation
  tear cuts to expand and to sever a connection between the printed antenna and the
  integrated circuit chip.
- 12. (Cancelled)
- 13. (Currently amended) The method of claim 12 21, further including the step of: applying a release liner to the adhesive.

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- 14. (New) The tag of claim 3, further including:a release liner attached to said adhesive.
- 15. (New) The tag of claim 3, further including: a hologram on the label material.
- 16. (New) The tag of claim 3, further including: microprinting on the label material.
- 17. (New) The tag of claim 8, further including: a release liner attached to said adhesive.
- 18. (New) The tag of claim 7, further including: a release liner attached to said adhesive.

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19. (New) The tag of claim 7, further including: a hologram on the label material.

20. (New) The tag of claim 7, further including: microprinting on the label material.

21. (New) A method of fabricating a tamper evident RFID tag, comprising the steps of: embedding the RFID transponder of claim 11 into a label material, and applying an adhesive to a backside of the label material.

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